

A2

while said wafer is in said first position, spraying a third volume of rinse solution against said wafer and rotating said wafer at a rate such that substantially all of said third volume of rinse solution enters said annular waste inlet.

24. [New] The method of Claim 23 wherein said second volume of rinse solution is smaller than said third volume of rinse solution.

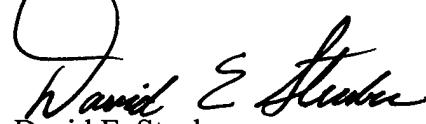
REMARKS

Claims 1-16 have been canceled, and new Claims 17-24 have been added.

EXPRESS MAIL LABEL NO.

EL 710 206 326 US

Respectfully submitted,

  
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